



Schena EZ-Cutter Operating Instructions

WARNING- Use extreme Caution while operating this instrument because the cutting blade is very sharp and can inflict harm to the user if not operated properly.

INSTRUCTIONS:

1. Carefully open the bottom drain on the pouch and insert the cutter handle with the threaded rod facing up until it pokes through the pilot hole in the wafer.
2. Center the threaded rod in the hole and then **CAREFULLY** thread the cutting instrument on the threaded rod and turn clockwise until it reaches the wafer size template. Align the cutting blade with the proper size and slowly turn the handle until it begins to cut the wafer (See Figure 1.).
3. The handle must be held firmly to counter-act the torque of the cutter as it is turned clockwise until it reaches the nylon cutting pad stop. This means the hole cutting operation has been completed.
4. Reverse the direction of the cutter to counter clockwise and remove the cutting instrument from the threaded rod. The cutting operation is complete and there should be a perfect hole with no burrs or rough edges (See Figure 2.). Remove the scrap piece from the cutter carefully using the pointed end of a pair of scissors or similar object to extract the scrap piece.
5. After several uses, residual adhesive material may accumulate on the cutting blade. This can be removed using Williams Lectric Shave solution on a piece of cloth. Use extreme **CAUTION** because the blade is very sharp.



Figure 1.



Figure 2.

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